



NOW PART OF



Reliability Data Report Product Family R413

LTC987 / LTC1726 / LTC1727 / LTC1728 /
LTC1921 / LTC1985 / LTC2369 / LTC2900 /
LTC2901 / LTC2902 / LTC2903 / LTC2904 /
LTC2905 / LTC2906 / LTC2907 / LTC2908 /
LTC2909 / LTC2910 / LTC2911 / LTC2912 /
LTC2913 / LTC2914 / LTC2915 / LTC2916 /
LTC2917 / LTC2918 / LTC2919 / LTC2920 /
LTC2923 / LTC2924 / LTC2925 / LTC2926 /
LTC2927 / LTC2928 / LTC2930 / LTC2931 /
LTC2932 / LTC2950 / LTC2951 / LTC2954 /
LTC4150 / LTC4257 / LTC4261 / LTC4263 /
LTC4265 / LTC4267 / LTC4273 / LTC4301 /
LTC4302 / LTC4354

Reliability Data Report

Report Number: R413

Report generated on: Mon Mar 05 10:50:54 PST 2018

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2,3}
QFN/DFN	3538	0421	1614	1356	0
SSOP/TSSOP	8905	0213	1709	1170	0
SOIC/MSOP	2131	9914	1550	1634	0
SOT	1138	0346	1201	997	0
Totals	15,712	-	-	5,157	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) ⁴	No. of FAILURES
QFN/DFN	356	0746	1531	923	0
Totals	356	-	-	923	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	10020	0325	1640	846	0
SSOP/TSSOP	7369	0436	1709	397	0
SOIC/MSOP	13453	9924	1712	735	0
SOT	42278	0004	1713	2227	0
Totals	73,120	-	-	4,205	0

TEMP CYCLE FROM -40 TO 125 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	25	1349	1349	25	0
Totals	25	-	-	25	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SSOP/TSSOP	3308	0436	1645	1182	0
QFN/DFN	9167	0325	1640	2670	0
SOIC/MSOP	14815	9924	1712	2198	0
SOT	5969	0004	1713	1303	0
Totals	33,259	-	-	7,353	0

(1) Assumes Activation Energy = 0.7 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =2.3 FITS
(3) Mean Time Between Failure in Years = 49683.15
(4) Assumes 20X Acceleration from 85 °C to +130 °C
Note 1: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	8379	0325	1640	1998	0
SSOP/TSSOP	3434	0650	1645	748	0
SOIC/MSOP	11063	9924	1712	1668	0
SOT	6251	0004	1713	1267	0
Totals	29,127	-	-	5,681	0
POWER CYCLE FROM 50 TO 100 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	44	1349	1349	44	0
Totals	44	-	-	44	0
HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	940	0743	1640	940	0
SSOP/TSSOP	50	1018	1018	25	0
Totals	990	-	-	965	0
HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	581	1349	1550	581	0
SSOP/TSSOP	150	1018	1514	75	0
SOIC/MSOP	448	0838	1631	324	0
SOT	348	0831	1228	323	0
Totals	1,527	-	-	1,303	0